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Synthetic resin compsn. with good mould release property - contg. silicon-contg. synthetic resin and silicone cpd. obtd. by reacting silicone cpd. with polypolyorganosiloxane

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Abstract (Basic): JP 5086295 A

The compsn. comprises 100 pts.wt. of (A) synthetic resin and 0.01-100 pts.wt. of (B) silicone resin consisting of 30-90 mol.% of (a) RSiO1.5, 0-80 mol.% of (b) R2SiO, 1-70 mol.% of (c) R3SiO0.5 and 0-50 mol.% of (d) SiO2 (where R are opt. substd. monovalent hydrocarbon gps.). (B) consists of 50-99 mol.% of RSiO1.5 and 1-50 mol.% of R3SiOO.5 (B) is obtd. by reacting 5-100 pts.wt. of silicone cpd. of formula (R2aSi)cZ (1) with 100 pts.wt. of polyorganosiloxane of formula R1a Si(OH)bO((4-a-b)/2) (2) and having silanol gp. in the mol.. In (I), R2 is same as R; and c is 1 or 2; when c is 1, Z is H, hydroxyl gp. or hydrolysable gp.; when c is 2, Z is -O-, -N(X)- or -S- (where X is H, 1-4C monovalent hydrocarbon gp. or R23Si-). In (2), R1 is same as R; a = 0.2-2.0; b = 0.001-3; and a+b is less than 4. (B) is a thermoplastic resin which has a softening point of above 50 deg.C. and is soluble in organic solvent. (A) includes thermoplastic, thermosetting and radiation curing resins, etc., The synthetic resin compsn. is used for film, coating and moulded prods..

ADVANTAGE - The compsn. has excellent mould release property, wear resistance, moisture-proofness, processability, water repellency and high surface lustre.

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Title Terms: SYNTHETIC; RESIN; COMPOSITION; MOULD; RELEASE; PROPERTIES; CONTAIN; SILICON; CONTAIN; SYNTHETIC; RESIN; SILICONE; COMPOUND; OBTAIN; REACT; SILICONE; COMPOUND; POLY; ORGANO; POLYSILOXANE

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